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PRODUCT DATASHEET

Surface Mount PTC Devices

ASMD3425 Series Surface Mount PTC Devices



Features

- Symmetrical design
- Fast response to fault current
- Compact design saves board space
- RoHS compliant, Lead-Free and Halogen-Free

Applications

- HDMI 1.4 Source protection
- PDAs / digital cameras
- Game console port protection
- USB port protection-USB 2.0, 3.0 & OTG
- PC motherboards - plug and play protection
- RoHS, REACH compliant and Halogen free

Performance Specification

Model	V_{max} (V dc)	I_{max} (A)	I_{hold} @25°C (A)	I_{trip} @25°C (A)	P_d Typ. (W)	Maximum Time To Trip		Resistance	
						Current (A)	Time (Sec)	$R_{i min}$ (Ω)	R_{1max} (Ω)
ASMD3425-185	60	20	1.85	3.70	2.5	8.0	10.0	0.045	0.220
ASMD3425-200	60	20	2.00	4.00	2.5	8.0	10.0	0.040	0.200
ASMD3425-260	60	20	2.60	5.20	2.5	8.0	10.0	0.020	0.120
ASMD3425-300	36	40	3.00	6.00	2.5	8.0	20.0	0.010	0.060
ASMD3425-600	24	40	6.00	12.0	2.5	30.0	5.0	0.002	0.018
ASMD3425-700	24	40	7.00	14.0	2.5	35.0	5.0	0.002	0.016

I_{hold} = Hold Current. Maximum current device will not trip in 25°C still air.

I_{trip} = Trip Current. Minimum current at which the device will always trip in 25°C still air.

V_{max} = Maximum operating voltage device can withstand without damage at rated current (I_{max}).

I_{max} = Maximum fault current device can withstand without damage at rated voltage (V_{max}).

P_d = Power dissipation when device is in the tripped state in 25°C still air environment at rated voltage.

$R_{i min/max}$ = Minimum/Maximum device resistance prior to tripping at 25°C.

R_{1max} = Maximum device resistance is measured one hour post reflow.

CAUTION : Operation beyond the specified ratings may result in damage and possible arcing and flame

Environmental Specifications

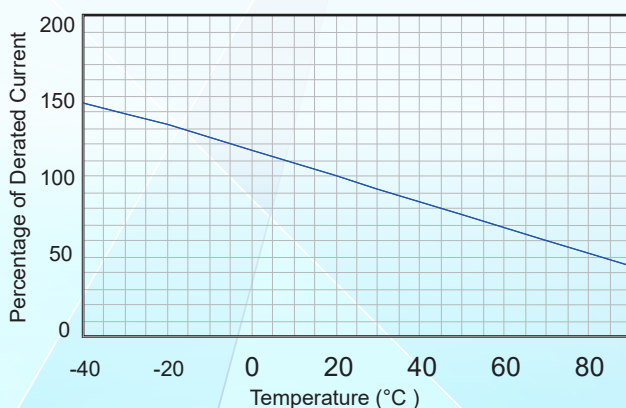
	Conditions	Resistance change
Passive aging	+85°C, 1000 hrs.	±5% typical
Humidity aging	+85°C, 85% R.H. , 1000 hours	±5% typical
Thermal shock	MIL-STD-202,Method107;+85°C to -40°C, 20 times	-30% typical
Resistance to solvent	MIL-STD-202,Method 215	No change
Vibration	MIL-STD-883,Method 2007,ConditionA;	No change
Ambient operating conditions : - 40 °C to +85 °C		
StorageConditions:+40°C Max. 70%RHMax. Packed in original packaging		
Maximum surface temperature of the device in the tripped state is 125 °C		

Test Procedures And Requirements

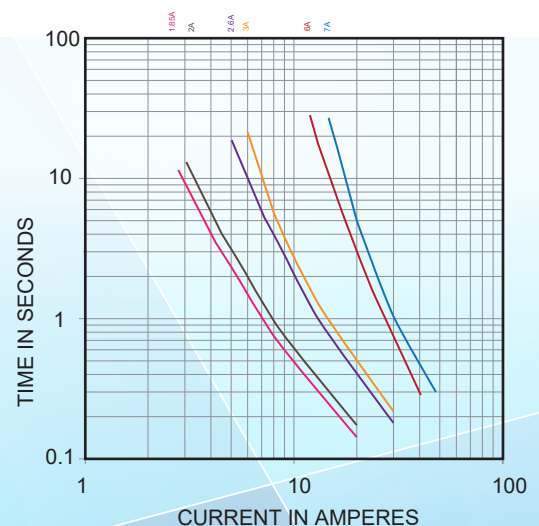
Text	Conditions	Accept/RejectCriteria
R0min	Resistance measurement at 25°C	$R0min \leq R \leq R1max$
R1max	Resistance measurement 1h after post trip	$R0min \leq R \leq R1max$
I-hold	Hold rated current 1800s without trip,@25°C	No trip
I-trip	Device must trip within 900s under rated current,@25°C	Trip
Max.time to trip	At specified current,25°C	$T \leq \text{max.time to trip(s)}$
TripCycleLife	Vmax,I _{max} ,100cycles	No arcing or burning
TripEndurance	Vmax,I _{max} 24h	No arcing or burning
Solderability	ANSI/J-STD-002	95%min.coverage

Environmental Characteristic

Thermal Derating Curve



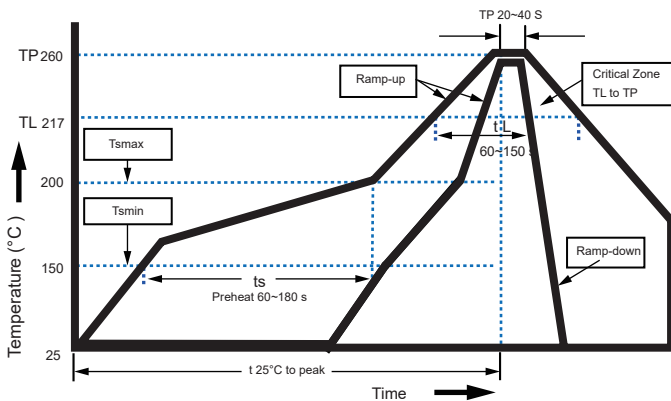
Average Time-Current Curve



Thermal Derating Chart

Model	Maximum ambient operating temperature (T_{mao}) vs. hold current (I_{hold})								
	- 40°C	- 20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
ASMD3425-185	2.82	2.54	2.22	1.85	1.57	1.22	0.82	0.49	0.23
ASMD3425-200	3.05	2.75	2.40	2.00	1.70	1.55	1.35	1.20	0.95
ASMD3425-260	3.97	3.58	3.12	2.60	2.21	2.02	1.76	1.56	1.24
ASMD3425-300	4.58	4.13	3.60	3.00	2.55	2.33	2.03	1.80	1.43
ASMD3425-600	9.15	8.25	7.20	6.00	5.10	4.65	4.05	3.60	2.85
ASMD3425-700	10.68	9.63	8.40	7.00	5.95	5.43	4.73	4.20	3.33

Soldering Parameters



- Recommended reflow methods: IR, vapor phase oven, hot air oven, N2 environment for lead-free.
- Recommended maximum paste thickness is 0.25mm. Devices can be cleaned using standard industry methods and solvents.
- Note 1: All temperature refer to topside of the package, measured on the package body surface.
- Note 2: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Profile Feature

Pb-Free Assembly

Average Ramp-Up Rate
($T_{\text{s max}}$ to T_{p})

3°C/second max.

Preheat

- Temperature Min($T_{\text{s min}}$)
- Temperature Max($T_{\text{s max}}$)
- Time($T_{\text{s min}}$ to $T_{\text{s max}}$)

150°C
200°C
60~180 seconds

Time maintained above:

- Temperature(T_{L})
- Time(t_{L})

217°C
60~150 seconds

Peak Temperature(T_{p})

260°C

Ramp-Down Rate

6°C/second max.

Time 25°C to Peak Temperature

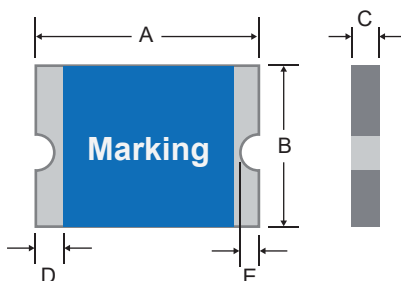
8 minutes max

Storage And Handling:

Storage conditions

0°C~ 35°C, 30% ~60% R.H.

Devices may not meet specified performance if storage conditions are exceeded.

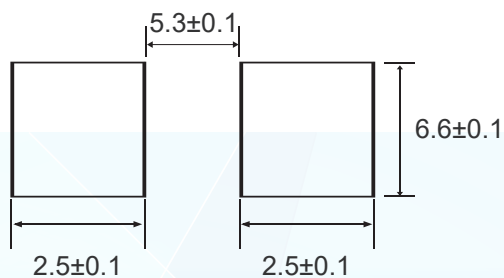
Physical Dimensions(mm.)


Model	A		B		C		D	E
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Min.
ASMD3425-185	8.30	9.00	6.00	6.70	1.00	1.80	0.30	0.25
ASMD3425-200	8.30	9.00	6.00	6.70	1.00	1.80	0.30	0.25
ASMD3425-260	8.30	9.00	6.00	6.70	1.00	1.80	0.30	0.25
ASMD3425-300	8.30	9.00	6.00	6.70	1.00	1.80	0.30	0.25
ASMD3425-600	8.30	9.00	6.00	6.70	1.00	1.80	0.30	0.25
ASMD3425-700	8.30	9.00	6.00	6.70	1.00	1.80	0.30	0.25

Termination Pad Characteristics

Terminal pad materials: Tin-plated Nickel-Copper(Solder Material:Matte Tin (Sn))

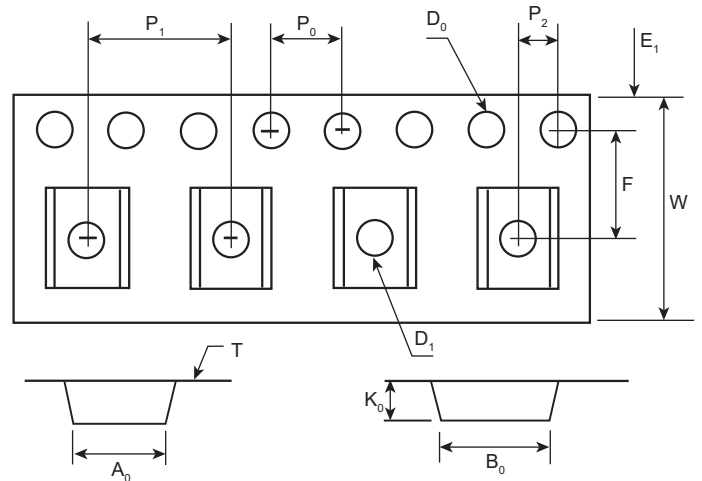
Terminal pad solder ability: Meets EIA specification RS186-9E and ANSI/J-STD-002 Category 3.

Recommended Pad Layout and Packaging Quantity

Recommended Pad Layout(mm)

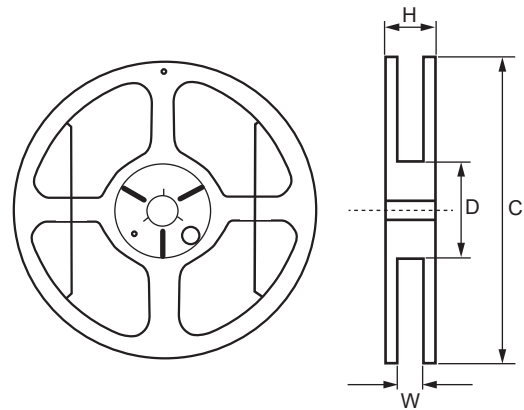
Part Number	Quantity
ASMD3425 Series	1,000 pcs/reel
Tape & reel packaging per EIA481-1	

Tape And Reel Specifications (mm)

Governing Specifications	EIA 481-1
W	16.0 ± 0.30
F	7.50 ± 0.10
E1	1.75 ± 0.10
D0	1.55 ± 0.05
D1	1.50 Min
P0	4.0 ± 0.10
P1	8.0 ± 0.10
P2	2.0 ± 0.10
A0	6.7 ± 0.10
B0	9.5 ± 0.10
T	0.30 ± 0.10
K0	1.85 ± 0.10
Leader	390 mm
Trailer	160 mm



REEL DIMENSIONS: EIA-481-1(mm)	
C	$\phi 178 \pm 3.0$
D	$\phi 60.2 \pm 0.5$
W	17.0 ± 0.2
H	19.5 ± 1.0


Part Number System

ASMD 3425 - □□□ - □□

Special Voltage Rating(Optional)

Holding Current Rating

Device Dimensions:
Length/width(Unit:1/100 inch) Size 3425 inch

Surface Mount Device

Application Notice

1. Operation of these PPTC devices beyond the stated maximum ratings could result in damage to the devices and lead to electrical arcing and/or fire ;

PPTC 器件在超过规定的最大值额定值运行可能会导致器件损坏以及导致电弧和/或火灾。

2. These PPTC devices are intended to protect against the effects of temporary over-current or over-temperature conditions and shall not be taken for use as switch.

PPTC 的作用是防止临时的过流或过温造成的不良影响，不能当作开关使用。

3. Exposure to lubricants, silicon-based oils, solvents, gels, electrolytes, acids, and other related or similar materials may adversely affect the performance of PPTC devices.

PPTC 接触润滑剂、硅基油、溶剂、凝胶、电解质、酸和其他相关或类似材料可能会对 PPTC 器件的性能有不利影响。

4. Circuits with inductance may generate a voltage above the rated voltage of the PPTC device and should be thoroughly evaluated within the user's application during the PPTC selection and qualification process.

带有电感的电路可能产生高于 PPTC 额定电压的电压，因此客户在选型和认定过程中应进行彻底的评估。

5. Please do not smash, clamp, pull, dent or twist by tool during assembling process , as they may result in the PPTC damage.

在装配过程中，避免有砸、挤、拉、扭等方式外力作用于 PPTC 本体上，因为它们可能导致 PPTC 损坏。

6. Hand-soldering of PPTC devices on boards is generally not recommended. Users shall define and verify this process if needed.

不推荐使用手工焊接的方式焊接 PPTC。如果需要，用户需要定义和验证此过程。

7. Recommended storage conditions should be followed at all times , The MSL classification of PPTC is grade 2a.

必须始终遵守推荐的保存条件要求， PPTC 的 MSL 等级为 2 a级。